Product/Process Change Notice - PCN 22_0169 Rev. -

Analog Devices, Inc. One Analog Way, Wilmington, MA 01887

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title: Notification of additional Assembly Location, ASE Korea for LTM4650 and LTM4650A

Publication Date: 22-Jul-2022

Effectivity Date: 24-Oct-2022 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:
Initial Release

Description Of Change:

ADI is adding ASE Korea as an alternate facility for LTM4650 and LTM4650A.

Reason For Change:

To qualify ASE Korea as an alternate assembly site to ensure the continuous availability of a reliable source of product supply.

Impact of the change (positive or negative) on fit, form, function & reliability:

This change will not impact fit, form, function, and reliability.

Product Identification *(this section will describe how to identify the changed material)*

After the PCN effectivity date, the date code of the product will be advised.

Summary of Supporting Information:

Qualification performed per Industry Standard Test Methods.

Supporting Documents

Attachment 1: Type: Qualification Results Summary

ADI_PCN_22_0169_Rev_-_LTM4650 BGA at ASE Korea Qualification Results Summary.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	**Europe:**	**Japan:**	**Rest of Asia:**
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_ROA@analog.com

Appendix A - Affected ADI Models				
Added Parts On This Revision - Product Family / Model Number (10)				
LTM4650 / LTM4650EY#PBF	LTM4650 / LTM4650IY	LTM4650 / LTM4650IY#PBF	LTM4650 / LTM4650MPY	LTM4650 / LTM4650MPY#PBF
LTM4650A / LTM4650AEV#PBF	LTM4650A / LTM4650AEY#PBF	LTM4650A / LTM4650AIV#PBF	LTM4650A / LTM4650AIY	LTM4650A / LTM4650AIY#PBF

Appendix B - Revision History			
Rev	**Publish Date**	**Effectivity Date**	**Rev Description**
Rev. -	22-Jul-2022	24-Oct-2022	Initial Release

LTM4650 BGA at ASE Korea Qualification Results Summary

Test Name	Specification	Conditions	Device	Sample Size (lot x samples)	Results
High Temperature Storage Life (HTSL)	JESD22-A103	150°C, 1,000 Hours	LTM4650	1 x 50	Pass
Temperature Cycling (TC) [1]	JESD22-A104	-55°C/+125°C, 1,000 Cycles	LTM4650	1 x 77	Pass
Thermal Shock (TS) [1]	JESD22-A106	-55°C/+125°C, 1,000 Cycles	LTM4650	1 x 77	Pass
Unbiased HAST (UHST) [1]	JESD22-A118	110C 85%RH 17.7 psia, P264	LTM4650	1 x 77	Pass

[1] These samples were subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: Bake: 48 hrs @ 125°C, Unbiased Soak: 192 hrs @ 30°C, 60%RH, Reflow: 3 passes through an oven with a peak temperature of 245°C.